

H610D4-P1

Version 1.0

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This device complies with Part 15 of the FCC Rules. Operation is subject to the following two conditions:

- (1) this device may not cause harmful interference, and
- (2) this device must accept any interference received, including interference that may cause undesired operation.

CALIFORNIA, USA ONLY

The Lithium battery adopted on this motherboard contains Perchlorate, a toxic substance controlled in Perchlorate Best Management Practices (BMP) regulations passed by the California Legislature. When you discard the Lithium battery in California, USA, please follow the related regulations in advance.

“Perchlorate Material-special handling may apply, see www.dtsc.ca.gov/hazardouswaste/perchlorate”



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Chapter 1 Introduction

Thank you for purchasing H610D4-P1 motherboard. In this documentation, Chapter 1 and 2 contains the introduction of the motherboard and step-by-step installation guides. Chapter 3 contains the operation guide of the software and utilities. Chapter 4 contains the configuration guide of the BIOS setup.



Because the motherboard specifications and the BIOS software might be updated, the content of this documentation will be subject to change without notice.

1.1 Package Contents

- H610D4-P1 Motherboard
- 1 x Quick Installation Guide
- 1 x SATA Data with Power Cable (Optional)
- 2 x Screws for M.2 Sockets (Optional)
- 1 x Screw for WiFi Module (Optional)

1.2 Specifications

- Platform**
- 6.7-in x 6.8-in, 17.0 cm x 17.2 cm
 - Solid Capacitor design

- CPU**
- Supports 13th Gen & 12th Gen Intel® Core™ Processors (LGA1700)
 - 4 Power Phase design
 - Supports Intel® Hybrid Technology
 - Supports Intel® Turbo Boost Max 3.0 Technology

- Chipset**
- Intel® H610

- Memory**
- Dual Channel DDR4 Memory Technology
 - 2 x DDR4 SO-DIMM Slots
 - Supports DDR4 non-ECC, un-buffered memory up to 3200*
 - * Please refer to Memory Support List on ASRock's website for more information. (<http://www.asrock.com/>)
 - Max. capacity of system memory: 64GB
 - Supports Intel® Extreme Memory Profile (XMP) 2.0

- Expansion Slot**
- 1 x M.2 Socket (Key E), supports type 2230 WiFi/BT module and Intel® CNVi (Integrated WiFi/BT)

- Graphics**
- Intel® UHD Graphics Built-in Visuals and the VGA outputs can be supported only with processors which are GPU integrated.
 - Intel® X^e Graphics Architecture (Gen 12)
 - Three graphics output options: 1x HDMI, 1 x DisplayPort 1.4 (DP1), 1 x DisplayPort 1.2 (DP2)
 - Supports Triple Monitor
 - Supports HDMI 2.1 TMDS Compatible with max. resolution up to 4K x 2K (4096x2160) @ 60Hz
 - Supports DisplayPort 1.4 with DSC (compressed) max. resolution up to 8K (7680x4320) @ 60Hz / 5K (5120x3200) @ 120Hz
 - Supports DisplayPort 1.2 with DSC (compressed) max. resolution up to 4K x 2K (4096x2304) @ 60Hz

- Supports HDCP 2.3 with HDMI 2.1 TMDS Compatible and DisplayPort 1.4/1.2 Ports

Audio

- Realtek ALC269 Audio Codec
- 1 x MIC IN
- 1 x Headset/Headphone

LAN

- Gigabit LAN 10/100/1000 Mb/s
- Giga PHY Intel® I219V
- Supports Wake-On-LAN
- Supports Lightning/ESD Protection
- Supports Energy Efficient Ethernet 802.3az
- Supports PXE

**Front
Panel I/O**

- 1 x Power Button
- 1 x Headphone/Headset Jack
- 1 x USB 3.2 Gen1 Type-A Port (Support ESD Protection)
- 1 x USB 3.2 Gen1 Type-C Port (Support ESD Protection)
- 2 x USB 2.0 Ports (Supports ESD Protection)
- 1 x Microphone Input Jack

**Rear Panel
I/O**

- 1 x DC Jack (Compatible with the 19V power adapter)*
- * Please use 90W power adapter for 35W CPU and 120W power adapter for 65W CPU.
- 1 x HDMI Port
- 2 x DisplayPort*
- * (1 x DP co-lay D-SUB)
- 4 x USB 3.2 Gen1 Type-A Ports (Supports ESD Protection)
- 1 x USB 3.2 Gen1 Type-C Port (Supports ESD Protection)
- 1 x RJ-45 LAN Port with LED (ACT/LINK LED and SPEED LED)

Storage

- 1 x SATA3 6.0 Gb/s Connector, supports NCQ, AHCI and Hot Plug
- 1 x Hyper M.2 Socket (M2_1, Key M), supports type 2280 PCIe Gen4x4 (64 Gb/s) mode*
- 1 x Ultra M.2 Socket (M2_2, Key M), supports type 2280 PCIe Gen3x4 (32 Gb/s) mode*
- * Supports NVMe SSD as boot disks

- Connector**
- 1 x COM Port Header
 - 1 x Chassis Intrusion Header
 - 1 x CPU Fan Connector (4-pin)
- * The CPU Fan Connector supports the CPU fan of maximum 1A (12W) fan power.
- 1 x Chassis Fan Connector (4-pin) (Smart Fan Speed Control)
 - 1 x Mono-Out Header

- BIOS Feature**
- AMI UEFI Legal BIOS with GUI support
 - ACPI 6.0 Compliant wake up events
 - SMBIOS 2.7 Support

- Hardware Monitor**
- Fan Tachometer: CPU, Chassis Fans
 - Quiet Fan (Auto adjust chassis fan speed by CPU temperature): CPU, Chassis Fans
 - Fan Multi-Speed Control: CPU, Chassis Fans
 - CASE OPEN detection
 - Voltage monitoring: +12V, +5V, +3.3V, CPU Vcore

- OS**
- Microsoft® Windows® 10 64-bit / 11 64-bit

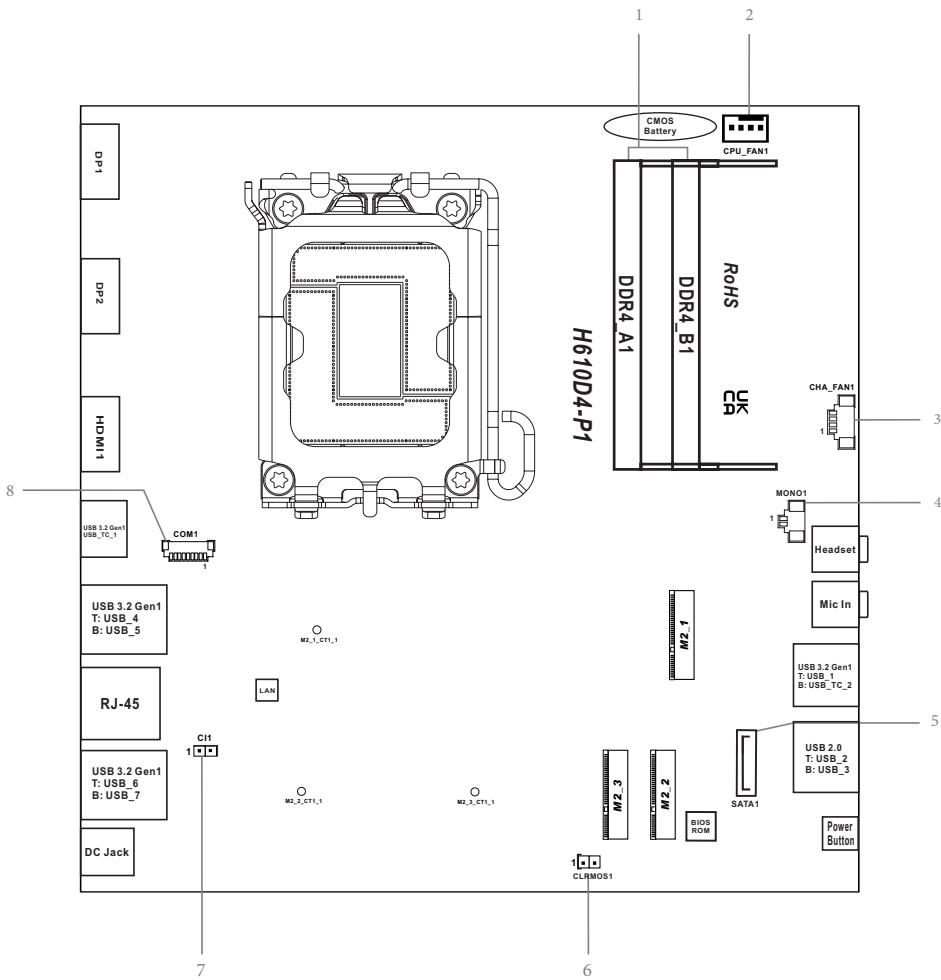
- Power**
- 1 x DC Jack (Supports 19V DC Power Adapters)

- Certifications**
- FCC, CE
 - ErP/EuP ready (ErP/EuP ready power supply is required)



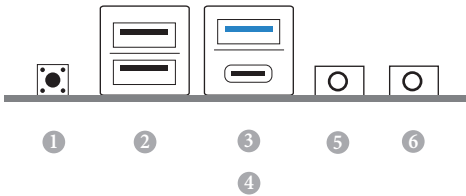
Please realize that there is a certain risk involved with overclocking, including adjusting the setting in the BIOS, applying Untied Overclocking Technology, or using third-party overclocking tools. Overclocking may affect your system's stability, or even cause damage to the components and devices of your system. It should be done at your own risk and expense. We are not responsible for possible damage caused by overclocking.

1.3 Motherboard Layout



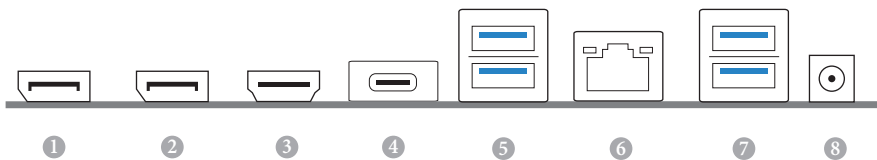
No.	Description
1	2 x 260-pin DDR4 SO-DIMM Slots (DDR4_A1, DDR4_B1)
2	CPU Fan Connector (CPU_FAN1)
3	Chassis Fan Connector (CHA_FAN1)
4	2.5W Mono Out Speaker Header (MONO1)
5	SATA3 Connector (SATA1)
6	Clear CMOS Jumper (CLRMOS1)
7	Chassis Intrusion Header (P305)
8	COM Port Header (COM1)

1.4 Front Panel



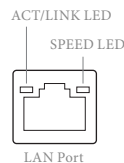
No.	Description	No.	Description
1	Power Button (SW1)	4	USB 3.2 Gen1 Type-C Port (USB_TC_2)
2	USB 2.0 Ports (USB_2_3)	5	Microphone Input
3	USB 3.2 Gen1 Type-A Port (USB_1)	6	Headphone/Headset Jack

1.5 Rear Panel



No.	Description	No.	Description
1	Display Port (DP1)	5	USB 3.2 Gen1 Type-A Ports (USB_4_5)
2	Display Port (DP2)*(co-lay D-SUB)	6	LAN RJ-45 Port*
3	HDMI Port	7	USB 3.2 Gen1 Type-A Ports (USB_6_7)
4	USB 3.2 Gen1 Type-C Port (USB_TC_1)	8	DC Jack**

* There are two LEDs on each LAN port. Please refer to the table below for the LAN port LED indications.



Activity / Link LED		Speed LED	
Status	Description	Status	Description
Off	No Link	Off	10Mbps connection
Blinking	Data Activity	Green	100Mbps connection
On	Link	Orange	1Gbps connection

** Please use a 19V power adapter for the DC jack. This jack accepts dual barrel plugs with an inner diameter of 2.5 mm and an outer diameter of 5.5 mm, where the inner contact is +19 (±10%) DC and the shell is (centre positive).

Please use a 90W adapter for the 35W CPU and a 120W adapter for the 65W CPU.

This motherboard is available with support for either 4-pin ATX 19V power or DC-in power supplies. Please do not use two kinds of power supplies at the same time! Doing so may damage the motherboard components and devices. When you use the DC-in power adapter, please use the onboard SATA power connector to get the power for HDDs.

Chapter 2 Installation

This is a Proprietary form factor motherboard. Before you install the motherboard, study the configuration of your chassis to ensure that the motherboard fits into it.

Pre-installation Precautions

Take note of the following precautions before you install motherboard components or change any motherboard settings.

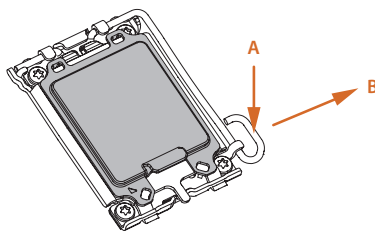
- Make sure to unplug the power cord before installing or removing the motherboard. Failure to do so may cause physical injuries to you and damages to motherboard components.
- In order to avoid damage from static electricity to the motherboard's components, NEVER place your motherboard directly on a carpet. Also remember to use a grounded wrist strap or touch a safety grounded object before you handle the components.
- Hold components by the edges and do not touch the ICs.
- Whenever you uninstall any components, place them on a grounded anti-static pad or in the bag that comes with the components.
- When placing screws to secure the motherboard to the chassis, please do not over-tighten the screws! Doing so may damage the motherboard.

2.1 Installing the CPU

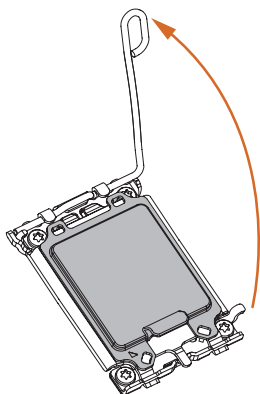


1. Before you insert the 1700-Pin CPU into the socket, please check if the **PnP cap** is on the socket, if the CPU surface is unclean, or if there are any **bent pins** in the socket. Do not force to insert the CPU into the socket if above situation is found. Otherwise, the CPU will be seriously damaged.
2. Unplug all power cables before installing the CPU.

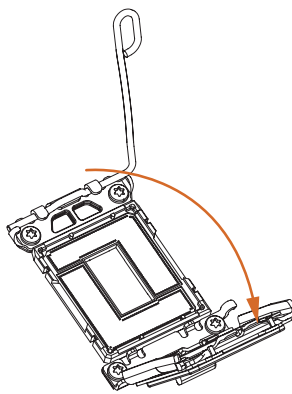
1

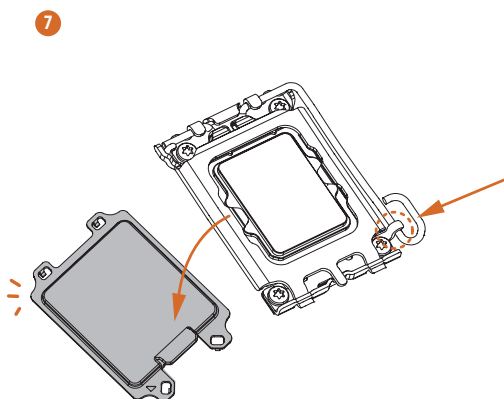
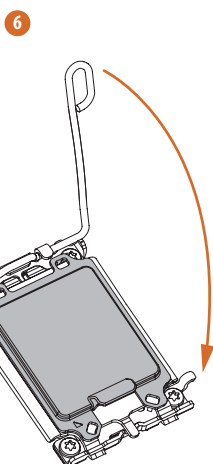
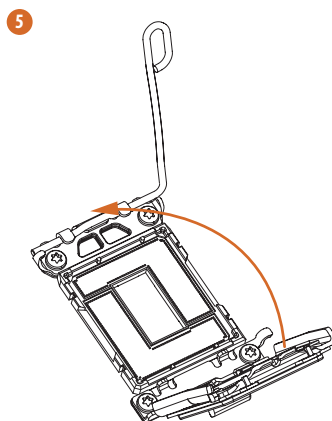
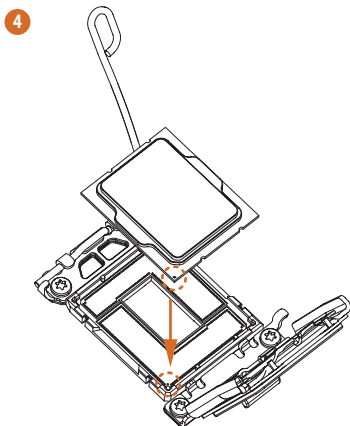


2



3

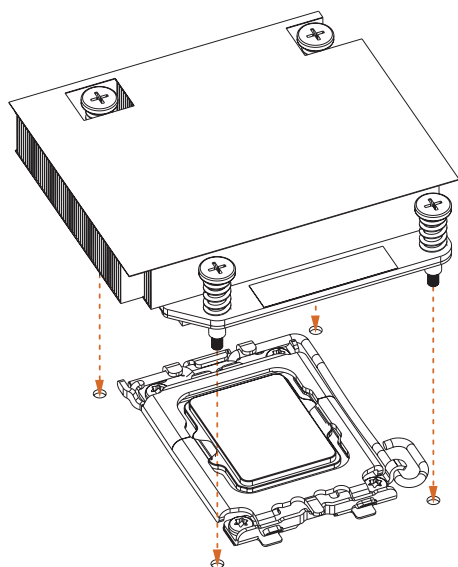






Please save and replace the cover if the processor is removed. The cover must be placed if you wish to return the motherboard for after service.

2.2 Installing the CPU Fan and Heatsink



2.3 Installing Memory Modules (SO-DIMM)

This motherboard provides two 260-pin DDR4 (Double Data Rate 4) SO-DIMM slots.

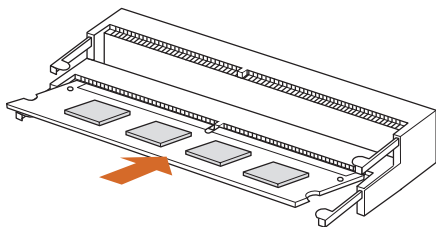


It is not allowed to install a DDR, DDR2 or DDR3 memory module into a DDR4 slot; otherwise, this motherboard and SO-DIMM may be damaged.

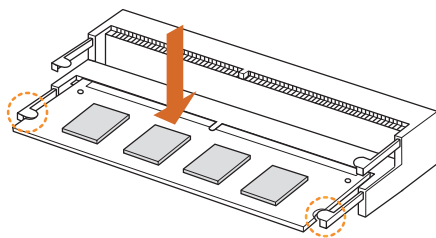


The SO-DIMM only fits in one correct orientation. It will cause permanent damage to the motherboard and the SO-DIMM if you force the SO-DIMM into the slot at incorrect orientation.

1. Carefully insert the SO-DIMM memory modules into the slot at a 30-degree angle.

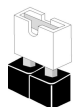


2. Push down until the modules snap into place.



2.4 Jumpers Setup

The illustration shows how jumpers are setup. When the jumper cap is placed on the pins, the jumper is “Short”. If no jumper cap is placed on the pins, the jumper is “Open”.



Short



Open

Clear CMOS Jumper
(CLR CMOS1)
(see p.5, No. 6)



2-pin Jumper

Short: Clear CMOS
Open: Default

CLR CMOS1 allows you to clear the data in CMOS. The data in CMOS includes system setup information such as system password, date, time, and system setup parameters. To clear and reset the system parameters to default setup, please turn off the computer and unplug the power cord, then use a jumper cap to short the pins on CLR CMOS1 for 3 seconds. Please remember to remove the jumper cap after clearing the CMOS. If you need to clear the CMOS when you just finish updating the BIOS, you must boot up the system first, and then shut it down before you do the clear-CMOS action.



If you clear the CMOS, the case open may be detected. Please adjust the BIOS option “Clear Status” to clear the record of previous chassis intrusion status.

2.5 Onboard Headers and Connectors



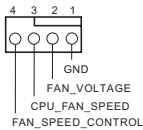
Onboard headers and connectors are NOT jumpers. Do NOT place jumper caps over these headers and connectors. Placing jumper caps over the headers and connectors will cause permanent damage to the motherboard.

Serial ATA3 Connector
(SATA1:
see p.5, No. 5)



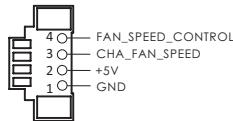
This SATA3 connector supports SATA data cables for internal storage devices with up to 6.0 Gb/s data transfer rate.

CPU Fan Connectors
(4-pin CPU_FAN1)
(see p.5, No. 2)



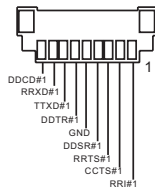
This motherboard provides a 4-Pin CPU fan (Quiet Fan) connector. If you plan to connect a 3-Pin CPU fan, please connect it to Pin 1-3.

Chassis Fan Connectors
(4-pin CHA_FAN1)
(see p.5, No. 3)



Please connect fan cables to the fan connectors and match the black wire to the ground pin.

Serial Port Header
(9-pin COM1)
(see p.5, No.8)



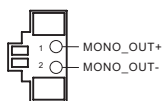
This COM1 header supports a serial port module.

Chassis Intrusion Header
(2-pin P305)
(see p.5, No. 7)



This motherboard supports CASE OPEN detection feature that detects if the chassis cove has been removed. This feature requires a chassis with chassis intrusion detection design.

2.5W Audio Amp Output
Header
(2-pin MONO1)
(see p.5, No. 4)



Please connect the chassis speaker to this header.

2.6 M.2 WiFi/BT Module and Intel® CNVi (Integrated WiFi/BT) Installation Guide

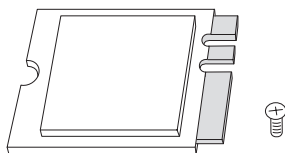
The M.2, also known as the Next Generation Form Factor (NGFF), is a small size and versatile card edge connector that aims to replace mPCIe and mSATA. The M.2 Socket (Key E) supports type 2230 WiFi/BT module and Intel® CNVi (Integrated WiFi/BT).

* The M.2 socket does not support SATA M.2 SSDs.



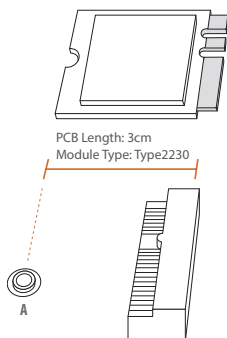
Before you install Intel® Integrated Connectivity (CNVi) module, be sure to turn off the AC power.

Installing the WiFi/BT module or Intel® CNVi (Integrated WiFi/BT)



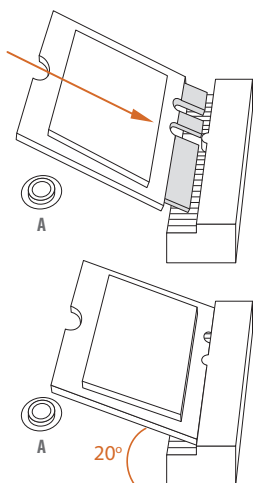
Step 1

Prepare a type 2230 WiFi/BT module or Intel® CNVi (Integrated WiFi/BT) and the screw.

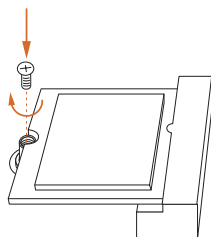


Step 2

Find the nut location to be used.

**Step 3**

Gently insert the WiFi/BT module or Intel® CNVi (Integrated WiFi/BT) into the M.2 slot. Please be aware that the module only fits in one orientation.

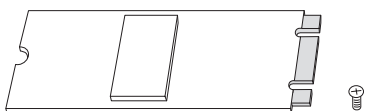
**Step 4**

Tighten the screw with a screwdriver to secure the module into place. Please do not overtighten the screw as this might damage the module.

2.7 M.2_SSD (NGFF) Module Installation Guide

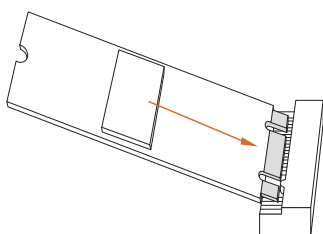
The M.2, also known as the Next Generation Form Factor (NGFF), is a small size and versatile card edge connector that aims to replace mPCIe and mSATA. The Hyper M.2 Socket (M2_1, Key M) supports type 2280 PCIe Gen4x4 (64 Gb/s) mode. The Ultra M.2 Socket (M2_2, Key M) supports type 2280 PCIe Gen3x4 (32 Gb/s) mode.

Installing the M.2_SSD (NGFF) Module



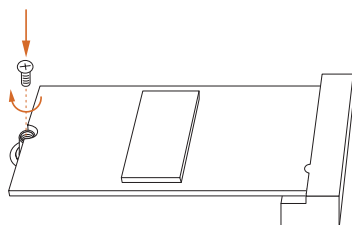
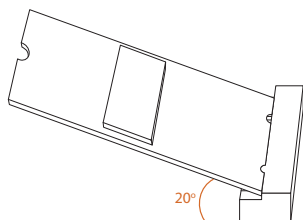
Step 1

Prepare a M.2_SSD (NGFF) module and the screw.



Step 2

Gently insert the M.2 (NGFF) SSD module into the M.2 slot. Please be aware that the M.2 (NGFF) SSD module only fits in one orientation.



Step 3

Tighten the screw with a screwdriver to secure the module into place. Please do not overtighten the screw as this might damage the module.

For the latest updates of M.2_SSD (NFGG) module support list, please visit our website for details.

Chapter 3 Auto Driver Installer

After you install the Windows OS and boot into the system, a notification will pop up to help you to install and update required drivers.



Chapter 4 UEFI SETUP UTILITY

4.1 Introduction

This section explains how to use the UEFI SETUP UTILITY to configure your system. You may run the UEFI SETUP UTILITY by pressing <F2> or right after you power on the computer, otherwise, the Power-On-Self-Test (POST) will continue with its test routines. If you wish to enter the UEFI SETUP UTILITY after POST, restart the system by pressing <Ctl> + <Alt> + <Delete>, or by pressing the reset button on the system chassis. You may also restart by turning the system off and then back on.



Because the UEFI software is constantly being updated, the following UEFI setup screens and descriptions are for reference purpose only, and they may not exactly match what you see on your screen.

4.2 EZ Mode

The EZ Mode screen appears when you enter the BIOS setup program by default. EZ mode is a dashboard which contains multiple readings of the system's current status. You can check the most crucial information of your system, such as CPU speed, DRAM frequency, SATA information, fan speed, etc.

Press <F6> or click the "Advanced Mode" button at the upper right corner of the screen to switch to "Advanced Mode" for more options.



No.	Function
1	Help
2	Load UEFI Defaults
3	Save Changes and Exit
4	Discard Changes
5	Change Language
6	Switch to Advanced Mode

4.3 Advanced Mode

The Advanced Mode provides more options to configure the BIOS settings. Refer to the following sections for the detailed configurations.

To access the EZ Mode, press <F6> or click the "EZ Mode" button at the upper right corner of the screen.

4.3.1 UEFI Menu Bar

The top of the screen has a menu bar with the following selections:

Main	For setting system time/date information
OC Tweaker	For overclocking configurations
Advanced	For advanced system configurations
Tool	Useful tools
H/W Monitor	Displays current hardware status
Security	For security settings
Boot	For configuring boot settings and boot priority
Exit	Exit the current screen or the UEFI Setup Utility

4.3.2 Navigation Keys

Use <←→> key or <→> key to choose among the selections on the menu bar, and use <↑> key or <↓> key to move the cursor up or down to select items, then press <Enter> to get into the sub screen. You can also use the mouse to click your required item.

Please check the following table for the descriptions of each navigation key.

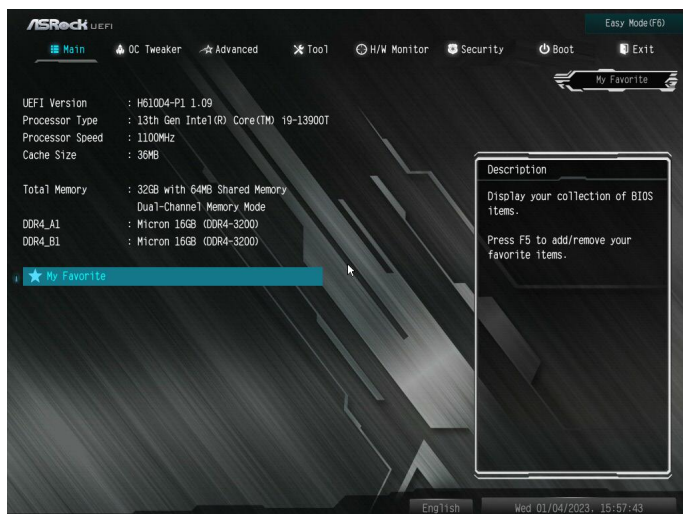
Navigation Key(s)	Description
+ / -	To change option for the selected items
<Tab>	Switch to next function
<PGUP>	Go to the previous page
<PGDN>	Go to the next page
<HOME>	Go to the top of the screen
<END>	Go to the bottom of the screen
<F1>	To display the General Help Screen
<F5>	Add / Remove Favorite
<F7>	Discard changes and exit the SETUP UTILITY
<F9>	Load optimal default values for all the settings
<F10>	Save changes and exit the SETUP UTILITY
<F12>	Print screen
<ESC>	Jump to the Exit Screen or exit the current screen

4.4 Main Screen

When you enter the UEFI SETUP UTILITY, the Main screen will appear and display the system overview.



The availability and location of BIOS settings can be different for different models and BIOS versions.

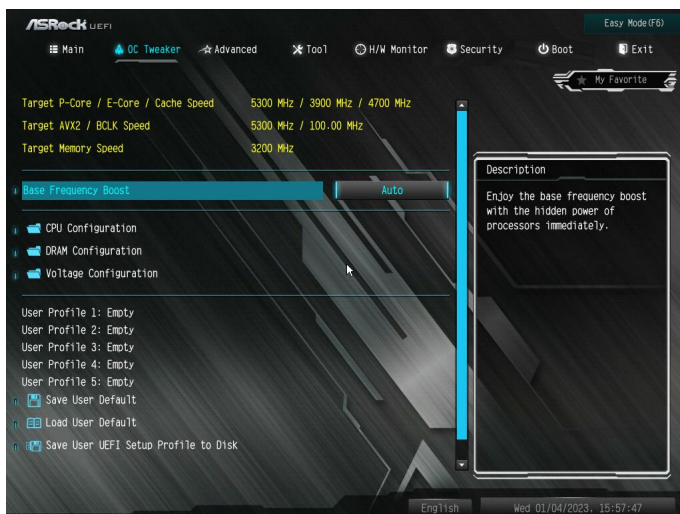


My Favorite

Display your collection of BIOS items. Press F5 to add/remove your favorite items.

4.5 OC Tweaker Screen

In the OC Tweaker screen, you can set up overclocking features.



Because the UEFI software is constantly being updated, the following UEFI setup screens and descriptions are for reference purpose only, and they may not exactly match what you see on your screen.

Base Frequency Boost

Enjoy the base frequency boost with the hidden power of processors immediately.

CPU Configuration

CPU Turbo Ratio Information

This item allows users to browse the CPU Turbo Ratio information.

CPU Configuration

CPU P-Core Ratio

The CPU speed is determined by the CPU P-Core Ratio multiplied with the BCLK. Increasing the CPU P-Core Ratio will increase the internal CPU clock speed without affecting the clock speed of other components.

AVX2 Ratio Offset

AVX2 Ratio Offset specifies a negative offset from the CPU Ratio for AVX workloads. AVX is a more stressful workload that lower the AVX ratio to ensure maximum possible ratio for SSE workloads.

Core Max OC Ratio

This option sets the maximum overclocking ratio for the CPU core. The allowable range is 0-80.

Core Ratio Extension Mode

Enable or disable core ratio above 85 Extension mode.

[Enabled] Max overclocking ratio limit as specified by OCMB 0x1 command is 120

[Disabled] Max overclocking ratio limit as specified by OCMB 0x1 command is 85.

CPU E-Core Ratio

The E-Core speed is determined by the E-Core Ratio multiplied with the BCLK. Increasing the E-Core Ratio will increase the internal E-Core clock speed without affecting the clock speed of other components.

CPU Cache Ratio

The CPU Internal Bus Speed Ratio. The maximum should be the same as the CPU Ratio.

Max Cache Ratio

The Max Internal Bus Speed Ratio. The maximum should be the same as the CPU Ratio.

Min Cache Ratio

The Min Internal Bus Speed Ratio. The maximum should be the same as the CPU Ratio.

CPU Flex Ratio Override

Allows you to enable or disable CPU Flex Ratio Programming. Flex Ratio can lower maximum non-turbo, especially for CPU without turbo function.

Configuration options: [Auto] [Enabled]

BCLK Frequency

The CPU speed is determined by the CPU Ratio multiplied with the BCLK. Increasing the BCLK will increase the internal CPU clock speed but also affect the clock speed of other components.

BCLK Spread Spectrum Mode

Enable Spread Spectrum to reduce electromagnetic interference for passing EMI tests. Disable to achieve higher clock speeds when overclocking.

BCLK Aware Adaptive Voltage

BCLK Aware Adaptive Voltage enable/disable. When enabled, pcode will be aware of the BCLK frequency when calculating the CPU V/F curves. This is ideal for BCLK OC to avoid high voltage overrides.

Boot Performance Mode

Select the performance state that the BIOS will set before OS handoff.

Ring to Core Ratio Offset

Disable Ring to Core Ratio Offset so the ring and core can run at the same frequency.

SA PLL Frequency Override

Configure SA PLL Frequency.

BCLK TSC HW Fixup

BCLK TSC HW Fixup disable during TSC copy from PMA to APIC.

FLL Overclock Mode

Nominal is good for normal core ratio overclocking. Elevated and Extremely Elevated are good for high BCLK OC.

Race To Halt (RTH)

Enable RTH will dynamically increase CPU frequency in order to enter Package C-State faster to reduce overall power.

Energy Efficient Turbo

Enable or disable Energy Efficient Turbo.

UnderVolt Protection

When UnderVolt Protection is enabled, user will not be able to program under voltage in OS runtime. It is recommended to keep it enabled by default.

[Enabled] This option allows BIOS undervolting. Undervolt Protection in Runtime is enabled.

[Disabled] No Undervolt Protection in Runtime.

Intel SpeedStep Technology

Intel SpeedStep technology allows processors to switch between multiple frequencies and voltage points for better power saving and heat dissipation.

Intel Turbo Boost Technology

Intel Turbo Boost Technology enables the processor to run above its base operating frequency when the operating system requests the highest performance state.

Intel Speed Shift Technology

Enable/Disable Intel Speed Shift Technology support. Enabling will expose the CPPC v2 interface to allow for hardware controlled P-states.

Intel Turbo Boost Max Technology 3.0

Intel Turbo Boost Technology enables the processor to run above its base operating frequency when the operating system requests the highest performance state.

Intel Thermal Velocity Boost Voltage Optimizations

This service controls thermal based voltage optimizations for processors that implement the Intel Thermal Velocity Boost (TVB) feature.

Dual Tau Boost

Enable Dual Tau Boost feature. This is only applicable for CMLS 35W/65W/125W skus. This item is only supported with processors with Config TDP support.

Long Duration Power Limit

Configure Package Power Limit 1 in watts. When the limit is exceeded, the CPU ratio will be lowered after a period of time. A lower limit can protect the CPU and save power, while a higher limit may improve performance.

Long Duration Maintained

Configure the period of time until the CPU ratio is lowered when the Long Duration Power Limit is exceeded.

Short Duration Power Limit

Configure Package Power Limit 2 in watts. When the limit is exceeded, the CPU ratio will be lowered immediately. A lower limit can protect the CPU and save power, while a higher limit may improve performance.

CPU Core Current Limit

Configure the current limit of the CPU core. A lower limit can protect the CPU and save power, while a higher limit may improve performance.

GT Current Limit

Configure the current limit of the GT slice. A lower limit can protect the CPU and save power, while a higher limit may improve performance.

DRAM Configuration

Memory Information

Allows users to browse the serial presence detect (SPD) and Intel extreme memory profile (XMP) for DDR4 modules.

DRAM Timing Configuration

DRAM Reference Clock

Select Auto for optimized settings.

DRAM Frequency

If [Auto] is selected, the motherboard will detect the memory module(s) inserted and assign the appropriate frequency automatically.

DRAM Gear Mode

High gear is good for high frequency.

Primary Timing

CAS# Latency (tCL)

The time between sending a column address to the memory and the beginning of the data in response.

RAS# to CAS# Delay (tRCD)

The number of clock cycles required between the opening of a row of memory and accessing columns within it.

Row Precharge (tRP)

The number of clock cycles required between the issuing of the precharge command and opening the next row.

RAS# Active Time (tRAS)

The number of clock cycles required between a bank active command and issuing the precharge command.

Command Rate (CR)

The delay between when a memory chip is selected and when the first active command can be issued.

Secondary Timing**Write Recovery Time (tWR)**

The amount of delay that must elapse after the completion of a valid write operation, before an active bank can be precharged.

Refresh Cycle Time (tRFC)

The number of clocks from a Refresh command until the first Activate command to the same rank.

RAS to RAS Delay (tRRD_L)

The number of clocks between two rows activated in different banks of the same rank.

RAS to RAS Delay (tRRD_S)

The number of clocks between two rows activated in different banks of the same rank.

Write to Read Delay (tWTR_L)

The number of clocks between the last valid write operation and the next read command to the same internal bank.

Write to Read Delay (tWTR_S)

The number of clocks between the last valid write operation and the next read command to the same internal bank.

Read to Precharge (tRTP)

The number of clocks that are inserted between a read command to a row precharge command to the same rank.

Four Activate Window (tFAW)

The time window in which four activates are allowed the same rank.

CAS Write Latency (tCWL)

Configure CAS Write Latency.

Third Timing

tREFI

Configure refresh cycles at an average periodic interval.

tCKE

Configure the period of time the DDR4 initiates a minimum of one refresh command internally once it enters Self-Refresh mode.

tRC

Use this item to change RAS# Cycle Time (tRC) Auto/Manual setting.

Turn Around Timing

Turn Around Timing Optimization

Auto is enabled in general case.

TAT Training Value

tRDRD_sg

Configure between module read to read delay.

tRDRD_dg

Configure between module read to read delay.

tRDRD_dr

Configure between module read to read delay.

tRDRD_dd

Configure between module read to read delay.

tRDWR_sg

Configure between module read to write delay.

tRDWR_dg

Configure between module read to write delay.

tRDWR_dr

Configure between module read to write delay.

tRDWR_dd

Configure between module read to write delay.

tWRRD_sg

Configure between module write to read delay.

tWRRD_dg

Configure between module write to read delay.

tWRRD_dr

Configure between module write to read delay.

tWRRD_dd

Configure between module write to read delay.

tWRWR_sg

Configure between module write to write delay.

tWRWR_dg

Configure between module write to write delay.

tWRWR_dr

Configure between module write to write delay.

tWRWR_dd

Configure between module write to write delay.

TAT Runtime Value

tRDRD_sg

Configure between module read to read delay.

tRDRD_dg

Configure between module read to read delay.

tRDRD_dr

Configure between module read to read delay.

tRDRD_dd

Configure between module read to read delay.

tRDWR_sg

Configure between module read to write delay.

tRDWR_dg

Configure between module read to write delay.

tRDWR_dr

Configure between module read to write delay.

tRDWR_dd

Configure between module read to write delay.

tWRRD_sg

Configure between module write to read delay.

tWRRD_dg

Configure between module write to read delay.

tWRRD_dr

Configure between module write to read delay.

tWRRD_dd

Configure between module write to read delay.

tWRWR_sg

Configure between module write to write delay.

tWRWR_dg

Configure between module write to write delay.

tWRWR_dr

Configure between module write to write delay.

tWRWR_dd

Configure between module write to write delay.

Round Trip Timing**Round Trip Timing Optimization**

Auto is enabled in general case.

Round Trip Level

Configure round trip level.

Initial RTL IO Delay Offset

Configure round trip latency IO delay initial offset.

Initial RTL FIFO Delay Offset

Configure round trip latency FIFO delay initial offset.

Initial RTL (MC0 C0 A1)

Configure round trip latency initial value.

Initial RTL (MC0 C1 A1)

Configure round trip latency initial value.

Initial RTL (MC1 C0 B1)

Configure round trip latency initial value.

Initial RTL (MC1 C1 B1)

Configure round trip latency initial value.

RTL (MC0 C0 A1)

Configure round trip latency value.

RTL (MC0 C1 A1)

Configure round trip latency value.

RTL (MC1 C0 B1)

Configure round trip latency value.

RTL (MC1 C1 B1)

Configure round trip latency value.

ODT Setting

Dimm ODT Training

ODT values will be optimized by Dimm On-Die Termination Training.

ODT WR (A1)

Configure the memory on die termination resistors' WR for channel A1.

ODT WR (B1)

Configure the memory on die termination resistors' WR for channel B1.

ODT NOM Rd (A1)

Configure the memory on die termination resistors' NOM Rd for channel A1.

ODT NOM Rd (B1)

Configure the memory on die termination resistors' NOM Rd for channel B1.

ODT PARK (A1)

Configure the memory on die termination resistors' PARK for channel A1.

ODT PARK (B1)

Configure the memory on die termination resistors' PARK for channel B1.

Advanced Setting

ASRock Timing Optimization

Configure the fast path through the MRC.

ASRock Second Timing Optimization

Configure the second fast path through the MRC.

MRC Training Respond Time

Try Slowest MRC Training.

Realtime Memory Timing

Configure the realtime memory timings.

[Enabled] The system will allow performing realtime memory timing changes after MRC_DONE.

Reset for MRC Failed

Reset system after MRC training is failed.

MRC Training on Warm Boot

When enabled, memory training will be executed when warm boot.

MRC Fast Boot

Enable Memory Fast Boot to skip DRAM memory training for booting faster.

Voltage Configuration

DRAM Voltage

Use this to configure DRAM Voltage. The default value is [Auto].

AVX Configuration

AVX2 Voltage Guardband Scale Factor

AVX2 Voltage Guardband Scale Factor controls the voltage guardband applied to AVX2 workloads. A value > 1.00 will increase the voltage guardband, and < 1.00 will decrease the voltage guardband.

FIVR Configuration

Core Voltage Mode

Selects between Adaptive and Override Voltage modes. In Override Mode, the voltage selected will be applied over all operating frequencies. In Adaptive mode, the voltage is interpolated only in turbo mode.

Extra Turbo Voltage

Specifies the extra turbo voltage applied while the IA Core is operating in turbo mode.

VF Offset Mode

Selects between Legacy and Selection modes. Need Reset System after enabling OverClocking Feature to initialize the default value. In Legacy Mode, setting a global offset for the entire VF curve. In Selection modes, setting a selected VF point.

VF Configuration Scope

Allows all cores VF curve or per-core VF curve configuration.

Core Voltage Offset

Specifies the offset voltage applied to the IA Core domain. This voltage is specified in millivolts.

Extra Turbo Voltage

Specifies the extra turbo voltage applied while Atom L2 is operating in turbo mode. Uses Mailbox MSR 0x150, cmd 0x10, 0x11. Range 0-2000 mV.

VF Offset Mode

Selects between Legacy and Selection modes. Need Reset System after enabling

OverClocking Feature to initialize the default value. In Legacy Mode, setting a global offset for the entire VF curve. In Selection modes, setting a selected VF point.

Ring Voltage Offset

Specifies the Offset Voltage applied to the Ring domain. This voltage is specified in millivolts. Uses Mailbox MSR 0x150, cmd 0x11. Range -500 to 500 mV.

GT Voltage Mode

Selects between adaptive and Override Voltage modes. In Override Mode the voltage selected will be applied over all operating frequencies. In Adaptive Mode the voltage is interpolated only in turbo mode. Uses Mailbox 0SR 0x150, cmd 0x10, 0x11.

Extra Turbo Voltage

Specifies the extra turbo voltage applied while GT is operating in turbo mode. Uses Mailbox MSR 0x150, cmd 0x10, 0x11. Range 0-2000 mV.

GT Voltage Offset

Specifies the Offset Voltage applied to the GT domain. This voltage is specified in millivolts. Uses Mailbox MSR 0x150, cmd 0x11. Range -500 to 500 mV.

Save User Default

Type a profile name and press enter to save your settings as user default.

Load User Default

Load previously saved user defaults.

Save User UEFI Setup Profile to Disk

It helps you to save current UEFI settings as an user profile to disk.

Load User UEFI Setup Profile from Disk

You can load previous saved profile from the disk.

4.6 Advanced Screen

In this section, you may set the configurations for the following items: CPU Configuration, Chipset Configuration, Storage Configuration, ACPI Configuration, USB Configuration and Trusted Computing.



Setting wrong values in this section may cause the system to malfunction.

UEFI Configuration

UEFI Setup Style

Select the default mode when entering the UEFI setup utility.

Active Page on Entry

Select the default page when entering the UEFI setup utility.

Full HD UEFI

When [Auto] is selected, the resolution will be set to 1920 x 1080 if the monitor supports Full HD resolution. If the monitor does not support Full HD resolution, then the resolution will be set to 1024 x 768. When [Disable] is selected, the resolution will be set to 1024 x 768 directly.

4.6.1 CPU Configuration



Processor P-Core Information

Press [Enter] to view P-Core Information.

Processor E-Core Information

Press [Enter] to view E-Core Information.

Intel Hyper Threading Technology

Intel Hyper Threading Technology allows multiple threads to run on each core, so that the overall performance on threaded software is improved.

Active Processor P-Cores

Allows you to select the number of cores to enable in each processor package.

Active Processor E-Cores

Allows you to select the number of E-Cores to enable in each processor package.

Note:

Number of P-Cores and E-Cores are looked at together. When both are {0,0}, Pcode will enable all cores.

CPU C States Support

Enable CPU C States Support for power saving. It is recommended to keep C6 and C7 all enabled for better power saving.

Enhanced Halt State (C1E)

Enable Enhanced Halt State (C1E) for lower power consumption.

CPU C6 State Support

Enable C6 deep sleep state for lower power consumption.

CPU C7 State Support

Enable C7 deep sleep state for lower power consumption.

Package C State Support

Enable CPU, PCIe, Memory, Graphics C State Support for power saving.

CFG Lock

This item allows you to disable or enable the CFG Lock.

C6DRAM

Enable/Disable moving of DRAM contents to PRM memory when CPU is in C6 state.

CPU Thermal Throttling

Enable CPU internal thermal control mechanisms to keep the CPU from overheating.

Intel AVX/AVX2

Enable/Disable the Intel AVX and AVX2 Instructions. This is applicable for Big Core only.

Intel Virtualization Technology

Intel Virtualization Technology allows a platform to run multiple operating systems and applications in independent partitions, so that one computer system can function as multiple virtual systems.

Hardware Prefetcher

Automatically prefetch data and code for the processor. Enable for better performance.

Adjacent Cache Line Prefetch

Automatically prefetch the subsequent cache line while retrieving the currently requested cache line. Enable for better performance.

Legacy Game Compatibility Mode

When enabled, pressing the scroll lock key will toggle the Efficient cores between being parked when Scroll Lock LED is on and un-parked when LED is off.

4.6.2 Chipset Configuration



Primary Graphics Adapter

Allows you to select a primary VGA.

Configuration options: [Auto] [Onboard] [PCIe1] (Options vary when you've installed a graphics card on your motherboard.)

Above 4G Decoding

Enable or disable 64bit capable Devices to be decoded in Above 4G Address Space (only if the system supports 64 bit PCI decoding).

VT-d

Intel® Virtualization Technology for Directed I/O helps your virtual machine monitor better utilize hardware by improving application compatibility and reliability, and providing additional levels of manageability, security, isolation, and I/O performance.

SR-IOV Support

If system has SR-IOV capable PCIe Devices, this option Enables or Disables Single Root IO Virtualization Support.

DMI Link Speed

Configure DMI Slot Link Speed. Auto mode is optimizing for overclocking.

M2_1 Link Speed

Configure M2_1 Slot Link Speed. Auto mode is optimizing for overclocking.

PCI Express Native Control

Select Enable for enhanced PCI Express power saving in OS.

PCIE ASPM Support

This option enables/disables the ASPM support for all CPU downstream devices.

PCH PCIE ASPM Support

This option enables/disables the ASPM support for all PCH PCIE devices.

DMI ASPM Support

This option enables/disables the control of ASPM on CPU side of the DMI Link.

PCH DMI ASPM Support

This option enables/disables the ASPM support for all PCH DMI devices.

Share Memory

Configure the size of memory that is allocated to the integrated graphics processor when the system boots up.

Intel(R) Ethernet Connection I219-V

Allows you to enable or disable Onboard LAN.

Configuration options: [Enabled] [Disabled]

Onboard HD Audio

Enable/disable onboard HD audio. Set to Auto to enable onboard HD audio and automatically disable it when a sound card is installed.

Onboard HDMI HD Audio

Enable audio for the onboard digital outputs.

Onboard WAN Device

Use this item to enable or disable the onboard WAN device.

Deep Sleep

Configure deep sleep mode for power saving when the computer is shut down.

Restore on AC/Power Loss

Select the power state after a power failure. If [Power Off] is selected, the power will remain off when the power recovers. If [Power On] is selected, the system will start to boot up when the power recovers.

GNA Device

Use this item to enable or disable the SA GNA device.

4.6.3 Storage Configuration



SATA Controller(s)

Enable/disable the SATA controllers.

SATA Mode Selection

AHCI: Supports new features that improve performance.

Hybrid Storage Detection and Configuration Mode

This item allows you select Hybrid Storage Detection and Configuration Mode.

SATA Aggressive Link Power Management

SATA Aggressive Link Power Management allows SATA devices to enter a low power state during periods of inactivity to save power. It is only supported by AHCI mode.

Hard Disk S.M.A.R.T.

S.M.A.R.T stands for Self-Monitoring, Analysis, and Reporting Technology. It is a monitoring system for computer hard disk drives to detect and report on various indicators of reliability.

VMD Configuration

Press [Enter] to view the followings items for VMD configurations.

Enable VMD Controller

Allows you to enable or disable the Intel VMD controller.

This following items appear when it is set to [Enabled].

Configuration options: [Enabled] [Disabled]

Enable VMD Global Mapping

Allows you to enable or disable the VMD Global Mapping.

Configuration options: [Enabled] [Disabled]

Map this Root Port under VMD

Allows you to map or unmap this Root Port to VMD. This item is allowed to be configured when "Enable VMD Global Mapping" is set to [Disabled].

Configuration options: [Enabled] [Disabled]

Root Port BDF details

Displays the Root Port BDF details.

4.6.4 ACPI Configuration



Suspend to RAM

Select disable for ACPI suspend type S1. It is recommended to select auto for ACPI S3 power saving.

PCIE Devices Power On

Allow the system to be waked up by a PCIE device and enable wake on LAN.

I219 LAN Power On

Allows the system to be waked up by the Onboard Intel LAN. Item name varies depending on the LAN type of your motherboard.

Configuration options: [Enabled] [Disabled]

RTC Alarm Power On

Allow the system to be waked up by the real time clock alarm. Set it to By OS to let it be handled by your operating system.

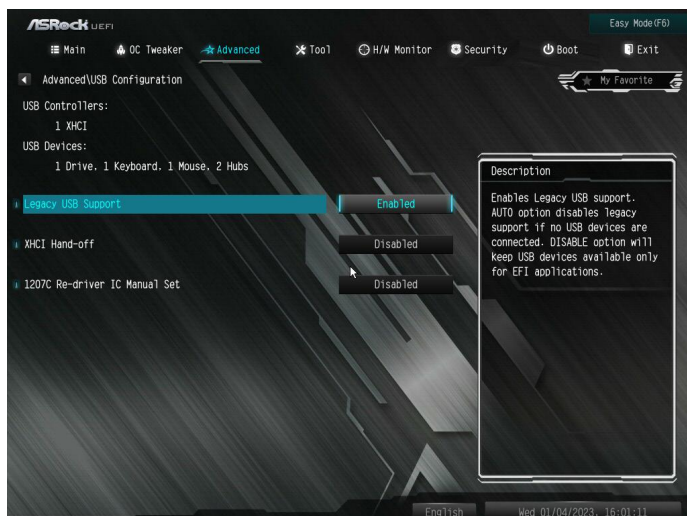
USB Keyboard/Remote Power On

Allow the system to be waked up by an USB keyboard or remote controller.

USB Mouse Power On

Allow the system to be waked up by an USB mouse.

4.6.5 USB Configuration



Legacy USB Support

Enable or disable Legacy OS Support for USB 2.0 devices. If you encounter USB compatibility issues it is recommended to disable legacy USB support. Select UEFI Setup Only to support USB devices under the UEFI setup and Windows/Linux operating systems only.

XHCI Hand-off

This is a workaround for OSes without XHCI hand-off support. The XHCI ownership change should be claimed by XHCI driver.

4.6.6 Trusted Computing



NOTE: Options vary depending on the version of your connected TPM module.

Security Device Support

Use this item to enable or disable BIOS support for security device. O.S. will not show Security Device. TCG EFI protocol and INT1A interface will not be available.

Active PCR banks

This item displays active PCR Banks.

Available PCR Banks

This item displays available PCR Banks.

SHA256 PCR Bank

Use this item to enable or disable SHA256 PCR Bank.

SHA384 PCR Bank

Use this item to enable or disable SHA384 PCR Bank.

SM3_256 PCR Bank

Use this item to enable or disable SM3_256 PCR Bank.

Pending Operation

Schedule an Operation for the Security Device.

NOTE: Your computer will reboot during restart in order to change State of the Device.

Platform Hierarchy

Use this item to enable or disable Platform Hierarchy.

Storage Hierarchy

Use this item to enable or disable Storage Hierarchy.

Endorsement Hierarchy

Use this item to enable or disable Endorsement Hierarchy.

Physical Presence Spec version

Select this item to tell OS to support PPI spec version 1.2 or 1.3. Please note that some HCK tests might not support version 1.3.

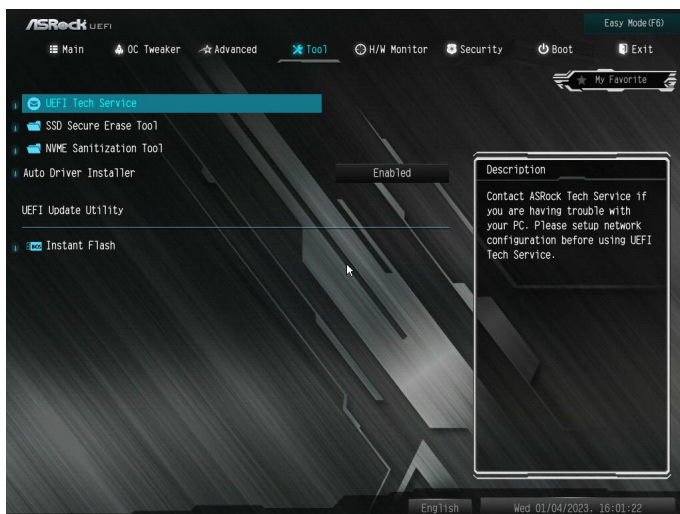
TPM 2.0 InterfaceType (CRB)

Select the Communication Interface to TPM 2.0 Device

Device Select

Use this item to select the TPM device to be supported. TPM 1.2 will restrict support to TPM 1.2 devices. TPM 2.0 will restrict support to TPM 2.0 devices. Auto will support both with the default set to TPM 2.0 devices. If TPM 2.0 devices are not found, TPM 1.2 devices will be enumerated.

4.7 Tools



UEFI Tech Service

Contact ASRock Tech Service if you are having trouble with your PC. Please setup network configuration before using UEFI Tech Service.

SSD Secure Erase Tool

All the SSD's listed that supports Secure Erase function.

NVME Sanitization Tool

After you Sanitize SSD, all user data will be permanently destroyed on the SSD and cannot be recovered.

Auto Driver Installer

If Auto Driver Installer is enabled, a notification will pop up to help users to install and update required drivers after booting into the system.

Instant Flash

Save UEFI files in your USB storage device and run Instant Flash to update your UEFI.

4.8 Hardware Health Event Monitoring Screen

This section allows you to monitor the status of the hardware on your system, including the parameters of the CPU temperature, motherboard temperature, fan speed and voltage.



Fan Tuning

Measure Fan Min Duty Cycle.

Fan-Tastic Tuning

Select a fan mode for CPU Fan, or choose Customize to set 5 CPU temperatures and assign a respective fan speed for each temperature.

CPU Fan 1 Setting

Select a fan mode for CPU Fan 1, or choose Customize to set 5 CPU temperatures and assign a respective fan speed for each temperature.

Chassis Fan 1 Setting

Select a fan mode for Chassis Fan 1, or choose Customize to set 5 CPU temperatures and assign a respective fan speed for each temperature.

Chassis Fan 1 Temp Source

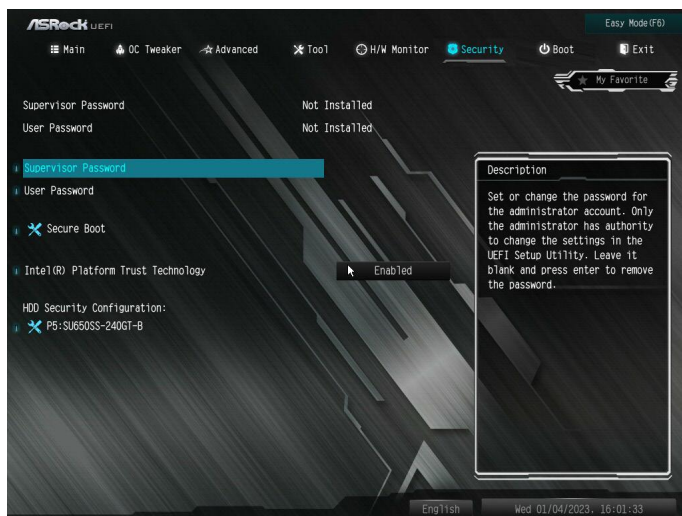
Select a fan temperature source for Chassis Fan 1.

Case Open Feature

Enable or disable Case Open Feature to detect whether the chassis cover has been removed.

4.9 Security Screen

In this section you may set or change the supervisor/user password for the system. You may also clear the user password.



Supervisor Password

Set or change the password for the administrator account. Only the administrator has authority to change the settings in the UEFI Setup Utility. Leave it blank and press enter to remove the password.

User Password

Set or change the password for the user account. Users are unable to change the settings in the UEFI Setup Utility. Leave it blank and press enter to remove the password.

Secure Boot

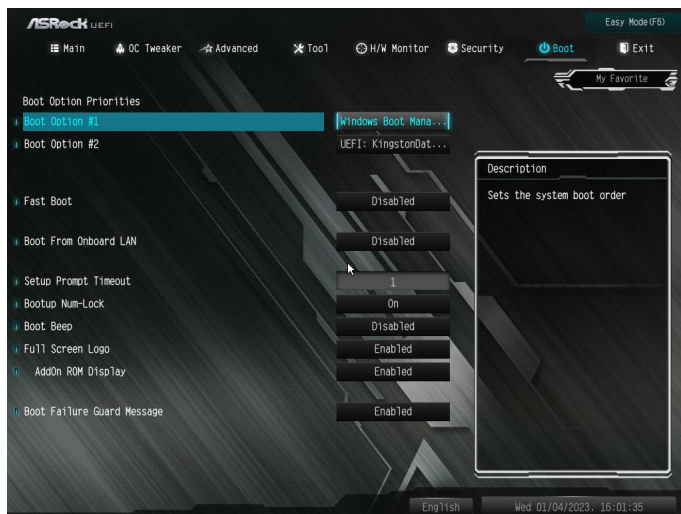
Use this item to enable or disable support for Secure Boot.

Intel(R) Platform Trust Technology

Enable/disable Intel PTT in ME. Disable this option to use discrete TPM Module.

4.10 Boot Screen

This section displays the available devices on your system for you to configure the boot settings and the boot priority.



Fast Boot

Fast Boot minimizes your computer's boot time. In fast mode you may not boot from an USB storage device. The VBIOS must support UEFI GOP if you are using an external graphics card. Please notice that Ultra Fast mode will boot so fast that the only way to enter this UEFI Setup Utility is to Clear CMOS or run the Restart to UEFI utility in Windows.

Boot From Onboard LAN

Allow the system to be waked up by the onboard LAN.

Setup Prompt Timeout

Configure the number of seconds to wait for the setup hot key.

Bootup Num-Lock

Select whether Num Lock should be turned on or off when the system boots up.

Boot Beep

Select whether the Boot Beep should be turned on or off when the system boots up. Please note that a buzzer is needed.

Full Screen Logo

Enable to display the boot logo or disable to show normal POST messages.

AddOn ROM Display

Enable AddOn ROM Display to see the AddOn ROM messages or configure the AddOn ROM if you've enabled Full Screen Logo. Disable for faster boot speed.

Boot Failure Guard Message

If the computer fails to boot for a number of times the system automatically restores the default settings.

4.11 Exit Screen



Save Changes and Exit

When you select this option the following message, “Save configuration changes and exit setup?” will pop out. Select [OK] to save changes and exit the UEFI SETUP UTILITY.

Discard Changes and Exit

When you select this option the following message, “Discard changes and exit setup?” will pop out. Select [OK] to exit the UEFI SETUP UTILITY without saving any changes.

Discard Changes

When you select this option the following message, “Discard changes?” will pop out. Select [OK] to discard all changes.

Load UEFI Defaults

Load UEFI default values for all options. The F9 key can be used for this operation.

Launch EFI Shell from filesystem device

Copy shellx64.efi to the root directory to launch EFI Shell.

DECLARATION OF CONFORMITY

Per FCC Part 2 Section 2.1077(a)



Product Name : Motherboard

Model Number : H610D4-P1

Conforms to the following specifications:

☒ FCC Part 15, Subpart B, Unintentional Radiators

Supplementary Information:

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

EU Declaration of Conformity

For the following equipment:

Motherboard

(Product Name)

H610D4-P1

(Model Designation / Trade Name)

EMC Directive – 2014/30/EU

EN 55032: 2015 / A11: 2020, EN 55035: 2017 / A11: 2020

EN IEC 61000-3-2: 2019, EN 61000-3-3: 2013

RoHS Directive - 2011/65/EU

2015/863/EU, EN IEC 63000:2018



(EU conformity marking)



EU Declaration of Conformity

Product:

Product Motherboard
Model H610D4-P1

Authorized Representative (UK-GB):

Name: Gary Tsui
Address: Bijsterhuizen 11-11, 6546 AR Nijmegen, The Netherlands
Contact person: Gary Tsui

This declaration is issued under the sole responsibility of the mentioned Manufacturer. The subject equipment under declaration is in conformity with the UK-GB Regulation(s) below:

The Electromagnetic Compatibility Regulations 2016 (S.I. 2016/1091)

EN 55032: 2015 / A11: 2020, EN 55035: 2017 / A11: 2020, EN IEC 61000-3-2: 2019, EN 61000-3-3: 2013

The Restriction of the Use of Certain Hazardous Substances in Electrical and Electronic Equipment Regulations 2012

2015/863/EU, EN IEC 63000:2018

The following manufacturer outside the UK-GB is responsible for this declaration: